3-Pin Supply Voltage Supervisors

Check for Samples: TPS3809J25, TPS3809L30, TPS3809K33, TPS3809I50

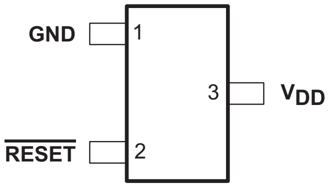
FEATURES

- **3-Pin SOT-23 Package**
- **Supply Current of 9 µA (Typical)**
- **Precision Supply Voltage Monitor 2.5 V, 3 V, 3.3 V, 5 V**
- **Pin-For-Pin Compatible With MAX 809**
- **Temperature Range: –40°C to +85°C**

APPLICATIONS

- **Applications Using DSPs, Microcontrollers, or Microprocessors**
- **Wireless Communication Systems**
- **Portable/Battery-Powered Equipment**
- **Programmable Controls**
- **Intelligent Instruments**
- **Industrial Equipment**
- **Notebook/Desktop Computers**
- **Automotive Systems**

DBV PACKAGE TOP VIEW)



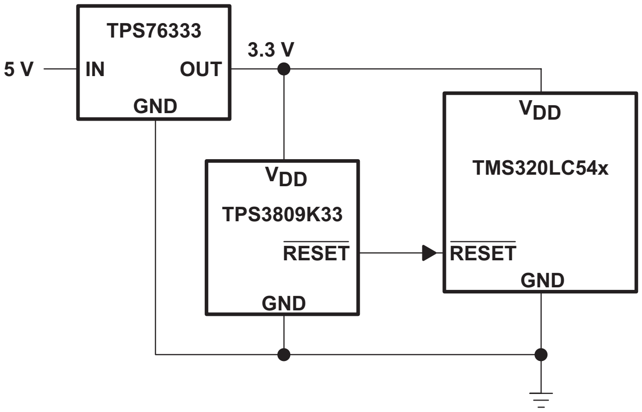
DESCRIPTION

The TPS3809 family of supervisory circuits provides circuit initialization and timing supervision, primarily for DSPs and processor-based systems.

During power-on, $\overline{\text{RESET}}$ is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supervisory circuit monitors V_{DD} and keeps $\overline{\text{RESET}}$ active as long as V_{DD} remains below the threshold voltage V_{IT}. An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, $t_{d(typ)}$ = 200 ms, starts after V_{DD} has risen above the threshold voltage V_{IT}. When the supply voltage drops below the threshold voltage V_{IT}, the output becomes active (low) again. No external components are required. All the devices of this family have a fixed sense-threshold voltage V_{IT} set by an internal voltage divider.

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in a 3-pin SOT-23. The TPS3809 devices are characterized for operation over a temperature range of –40°C to 85°C.

TYPICAL APPLICATION



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

AVAILABLE OPTIONS(1)

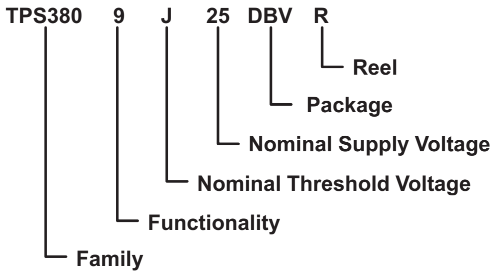
T_A	DEVICE NAME		THRESHOLD VOLTAGE	MARKING
–40°C to 85°C	TPS3809J25DBVR	TPS3809J25DBVT	2.25 V	PCZI
	TPS3809L30DBVR	TPS3809L30DBVT	2.64 V	PDAI
	TPS3809K33DBVR	TPS3809K33DBVT	2.93 V	PDBI
	TPS3809I50DBVR	TPS3809I50DBVT	4.55 V	PDCI

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this data sheet, or visit the device product folder at www.ti.com.

FUNCTION/TRUTH TABLE, TPS3809

$V_{DD} > V_{IT}$	$\overline{\text{RESET}}$
0	L
1	H

ORDERING INFORMATION



ABSOLUTE MAXIMUM RATINGS(1)(2)

Over operating free-air temperature range (unless otherwise noted).

	UNIT
Supply voltage, V_{DD}	7 V
All other pins	–0.3 V to 7 V
Maximum low-output current, I_{OL}	5 mA
Maximum high-output current, I_{OH}	–5 mA
Input-clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output-clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	–40°C to 85°C
Storage temperature range, T_{stg}	–65°C to 150°C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to GND. For reliable operation, the device should not be operated at 7 V for more than t = 1000h continuously.

DISSIPATION RATINGS

PACKAGE	$T_A < 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A < 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

RECOMMENDED OPERATING CONDITIONS

	MIN	MAX	UNIT
Supply voltage, V_{DD}	2	6	V
$\overline{\text{RESET}}$ current sink during startup		50	µA
Operating free-air temperature range, T_A	–40	+85	°C

ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range (unless otherwise noted).

PARAMETER			TEST CONDITIONS	TPS3800-xx, TPS3801-xx, TPS3802-xx			
				MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage		V_{DD} = 2.5 V to 6 V I_{OH} = –500 µA	V_{DD} –0.2			V
			V_{DD} = 3.3 V I_{OH} = –2 mA	V_{DD} –0.4			
			V_{DD} = 6 V I_{OH} = –4 mA	V_{DD} –0.4			
V_{OL}	Low-level output voltage		V_{DD} = 2 V to 6 V, I_{OL} = 500 µA			0.2	V
			V_{DD} = 3.3 V, I_{OL} = 2 mA			0.4	
			V_{DD} = 6 V, I_{OL} = 4 mA			0.4	
	Power-up reset voltage (1)		V_{DD} ≥ 1.1 V, I_{OL} = 50 µA			0.2	V
V_{IT-}	Negative-going input threshold voltage (2)	TPS3809J25	T_A = –40°C to 85°C	2.2	2.25	2.3	V
		TPS3809L30		2.58	2.64	2.7	
		TPS3809K33		2.87	2.93	2.99	
		TPS3809I50		4.45	4.55	4.65	
V_{hys}	Threshold hysteresis	TPS3809J25			30		mV
		TPS3809L30			35		
		TPS3809K33			40		
		TPS3809I50			60		
I_{DD}	Supply current		V_{DD} = 2 V, output unconnected		9	12	µA
			V_{DD} = 6 V, output unconnected		20	25	
C_i	Input capacitance		V_I = 0 V to V_{DD}		5		pF

(1) The lowest supply voltage at which $\overline{\text{RESET}}$ becomes active. $t_{r,\ VDD}$ ≥ 15 µs/V.

(2) To ensure the best stability of the threshold voltage, a bypass capacitor (0.1-µF ceramic) should be placed near the supply terminals.

TIMING REQUIREMENTS

at R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

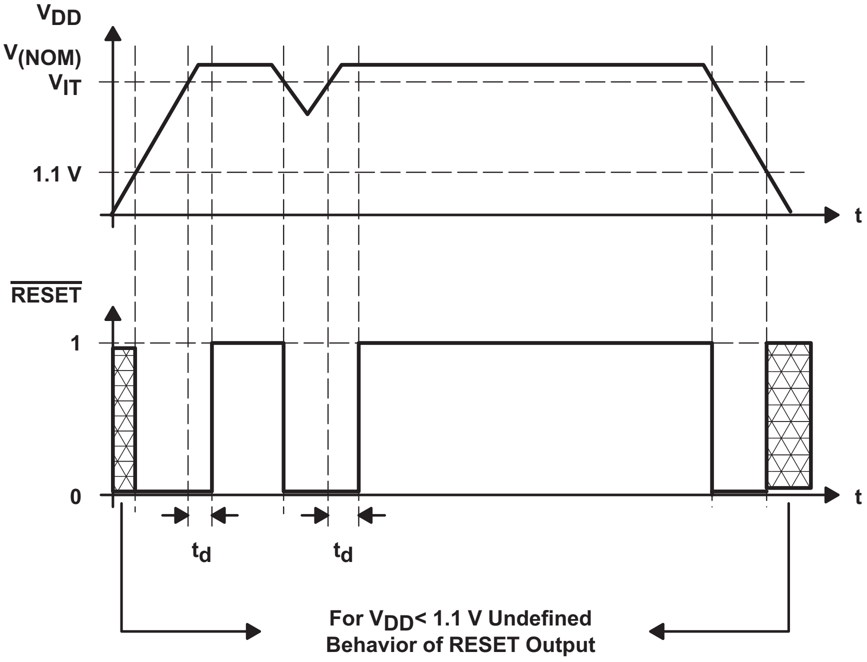
PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_w	Pulse width	at V_{DD}	$V_{DD} = V_{IT-} + 0.2$ V, $V_{DD} = V_{IT-} - 0.2$ V	3			µs

SWITCHING CHARACTERISTICS

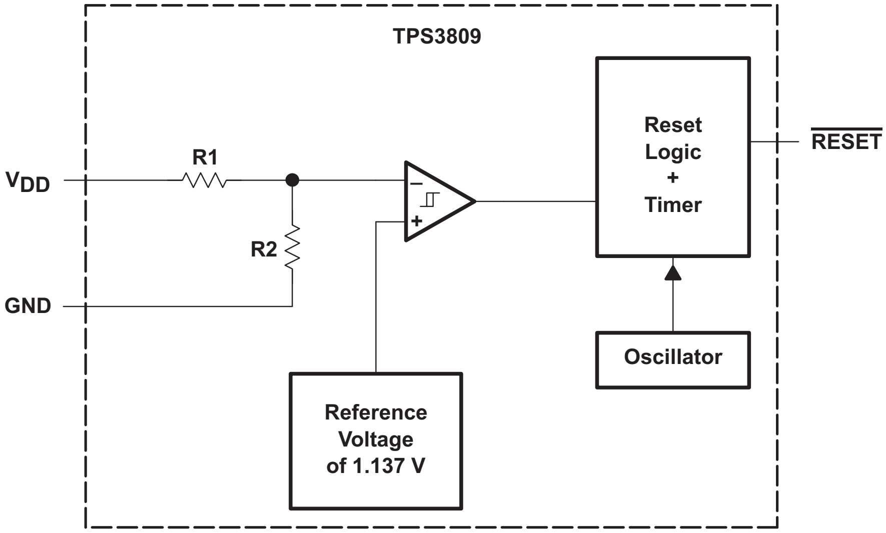
at R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_d	Delay time		$V_{DD} \geq V_{IT-} + 0.2$ V, See timing diagram	120	200	280	ms
t_{PHL}	Propagation (delay) time, high-to-low-level output	V_{DD} to $\overline{\text{RESET}}$ delay	$V_{IL} = V_{IT-} - 0.2$ V, $V_{IH} = V_{IT-} + 0.2$ V		1		µs

TIMING DIAGRAM



FUNCTIONAL BLOCK DIAGRAM



TYPICAL CHARACTERISTICS

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

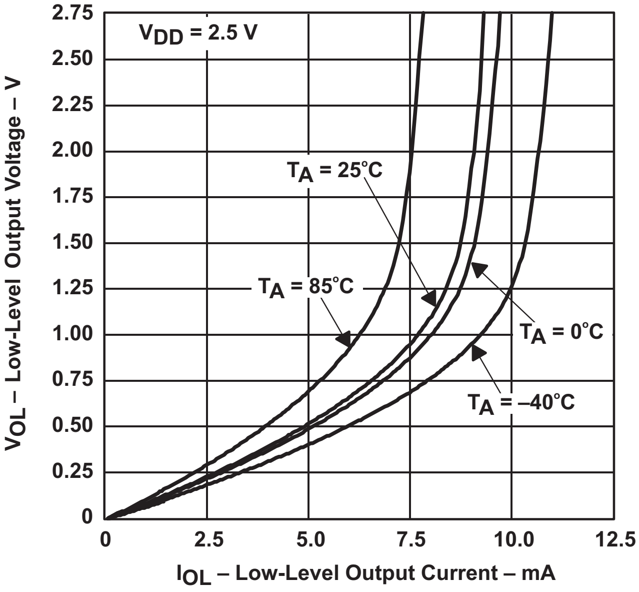


Figure 1.

SUPPLY CURRENT
vs
SUPPLY VOLTAGE

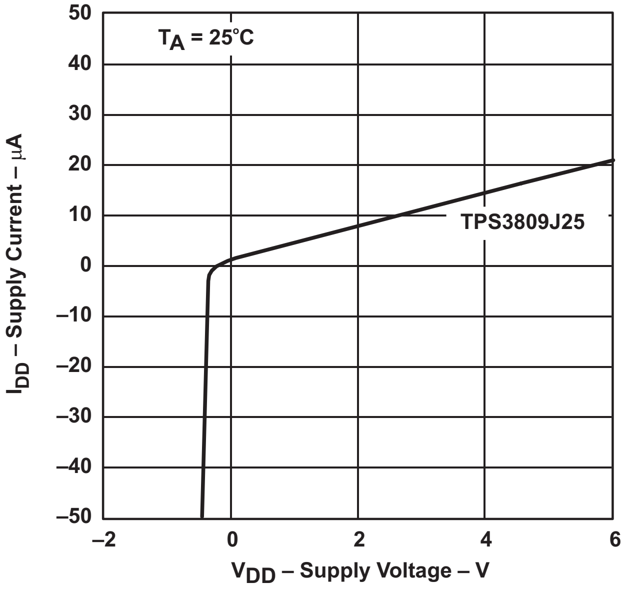


Figure 2.

HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

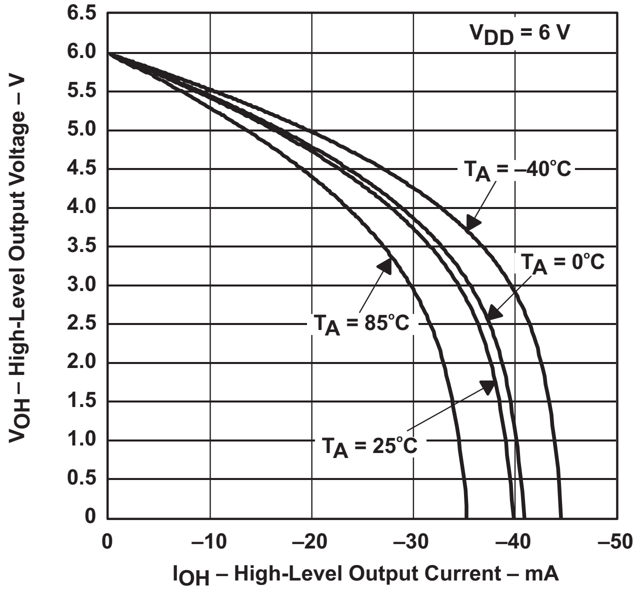


Figure 3.

HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

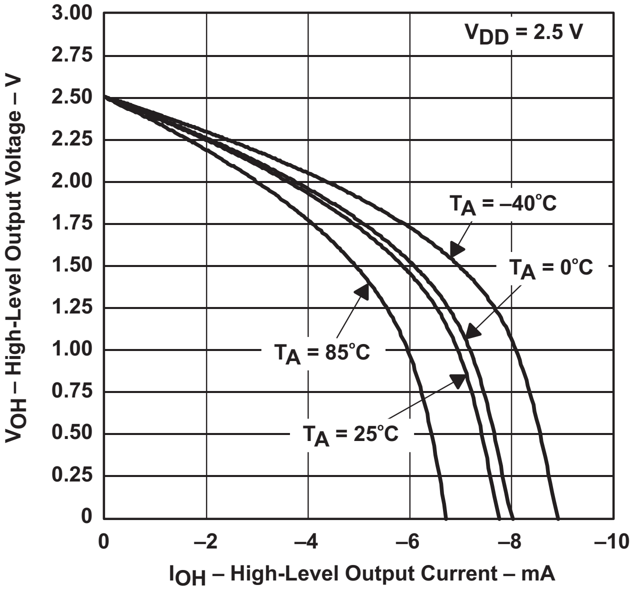


Figure 4.

TYPICAL CHARACTERISTICS (continued)

NORMALIZED INPUT THRESHOLD VOLTAGE vs FREE-AIR TEMPERATURE AT V_{DD}

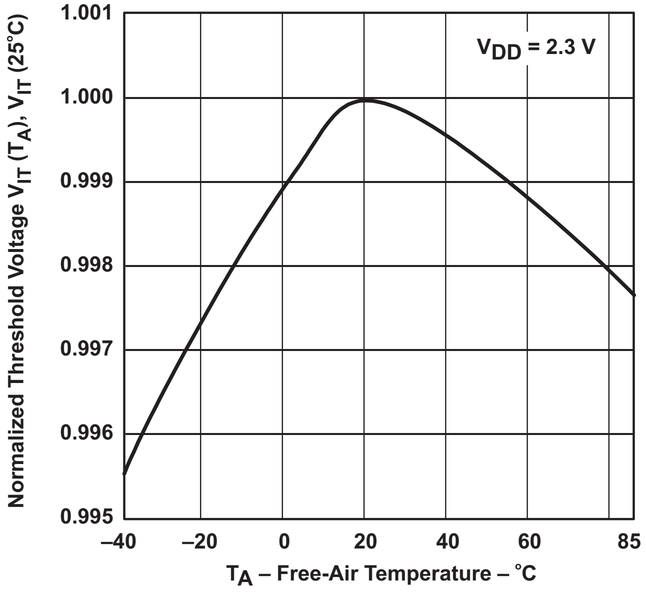


Figure 5.

NORMALIZED INPUT THRESHOLD VOLTAGE vs FREE-AIR TEMPERATURE AT V_{DD}

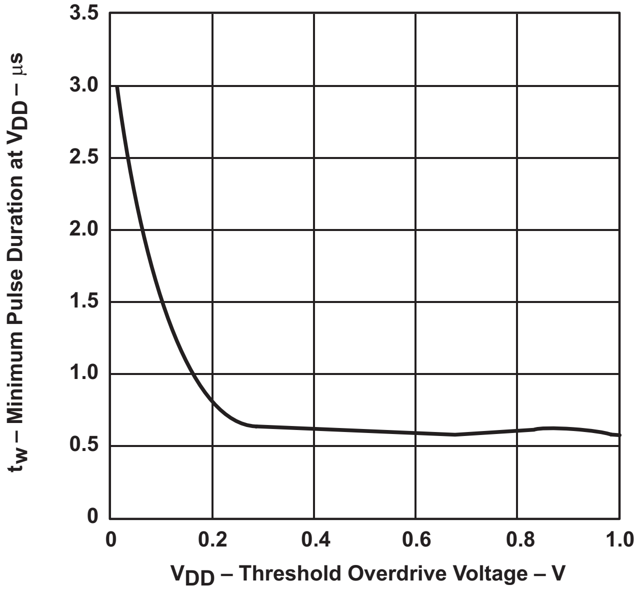


Figure 6.

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (July 2012) to Revision C	Page
• Changed front page and page flow to match current standard look and feel	1
• Changed "Operating junction temperature range" to "Operating free-air temperature range" in Absolute Maximum Ratings (typo)	2

Changes from Revision A (October 2010) to Revision B	Page
• Changed the Pull-up resistor value, $\overline{\text{RESET}}$ To: $\overline{\text{RESET}}$ current sink during startup in the Recommended Operating Conditions Table	2

Changes from Original (August 1999) to Revision A	Page
• Added Pull-up resistor value, $\overline{\text{RESET}}$ to the Recommended Operating Conditions Table	2

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3809I50DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU | Call TI	Level-1-260C-UNLIM	-40 to 85	PDCI	Samples
TPS3809I50DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDCI	Samples
TPS3809I50DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU | Call TI	Level-1-260C-UNLIM	-40 to 85	PDCI	Samples
TPS3809I50DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDCI	Samples
TPS3809J25DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI	Samples
TPS3809J25DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI	Samples
TPS3809J25DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCZI	Samples
TPS3809K33DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI	Samples
TPS3809K33DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI	Samples
TPS3809K33DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI	Samples
TPS3809K33DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDBI	Samples
TPS3809L30DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI	Samples
TPS3809L30DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI	Samples
TPS3809L30DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI	Samples
TPS3809L30DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PDAI	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

[4] There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

[5] Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

[6] Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF TPS3809I50, TPS3809K33, TPS3809L30 :

- Automotive: TPS3809I50-Q1, TPS3809K33-Q1, TPS3809L30-Q1

- Enhanced Product: TPS3809I50-EP, TPS3809K33-EP, TPS3809L30-EP

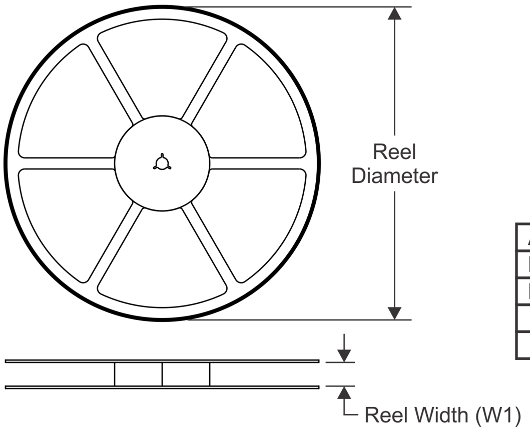
NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

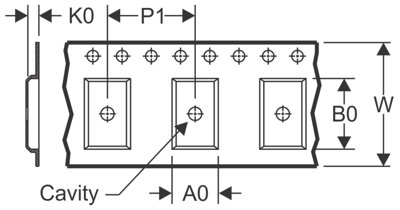
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

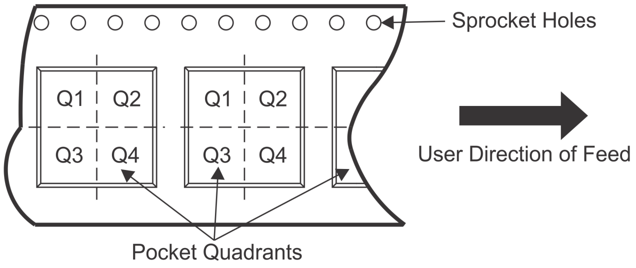


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

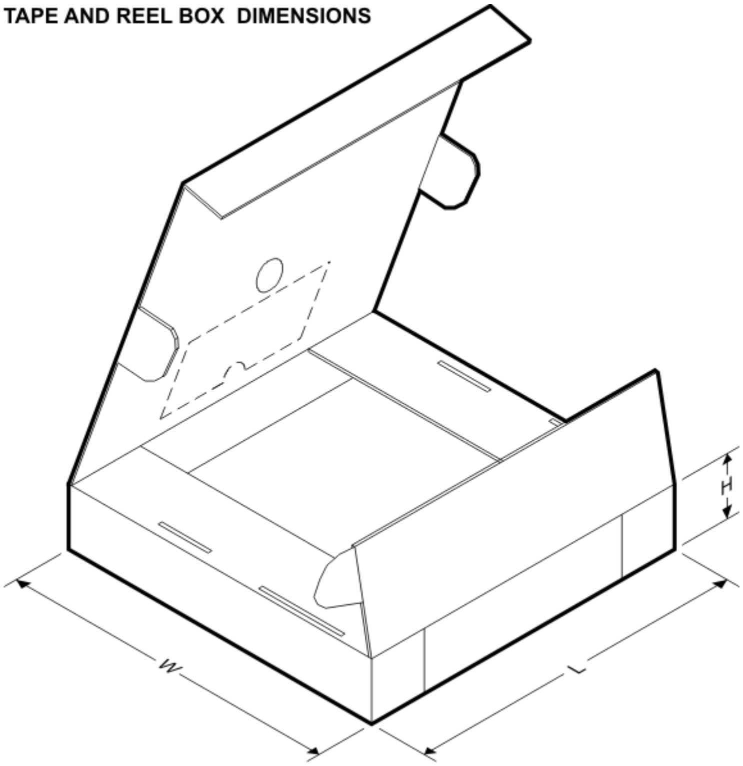
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3809I50DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809I50DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809J25DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809J25DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809K33DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809K33DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809L30DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809L30DBVT	SOT-23	DBV	3	250	178.0	8.4	3.3	3.2	1.47	4.0	8.0	Q3

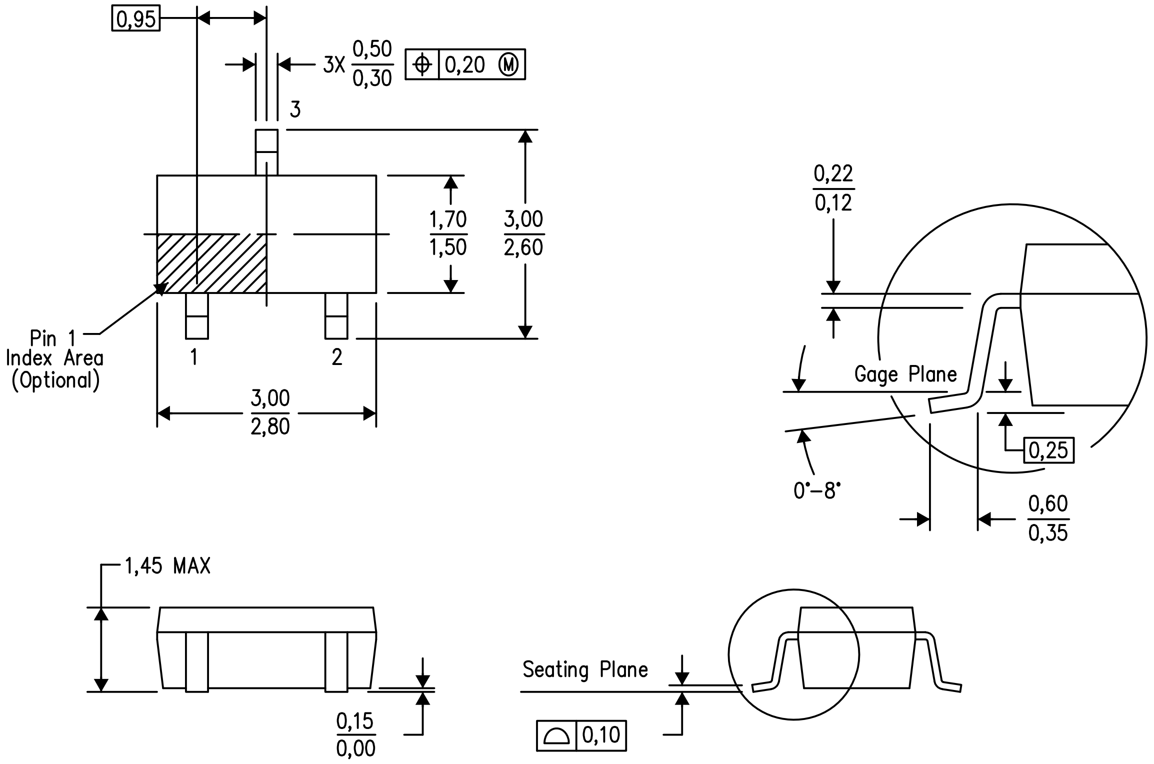
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3809I50DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809I50DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809J25DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809J25DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809K33DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809K33DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809L30DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809L30DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0

DBV (R-PDSO-G3) PLASTIC SMALL-OUTLINE PACKAGE



4073253-2/N 12/14

NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.

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